**TOSHIBA** 2SJ525

TOSHIBA FIELD EFFECT TRANSISTOR SILICON P CHANNEL MOS TYPE ( $L^2-\pi$ -MOS V)

# 2 S J 5 2 5

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS** 

#### • 4 V Gate Drive

• Low Drain-Source ON Resistance :  $R_{DS(ON)} = 0.1 \Omega$  (Typ.)

• High Forward Transfer Admittance :  $|Y_{fs}| = 4.5 \text{ S}$  (Typ.)

• Low Leakage Current :  $I_{DSS} = -100 \,\mu\text{A}$  (Max.)

 $(V_{DS} = -30 V)$ 

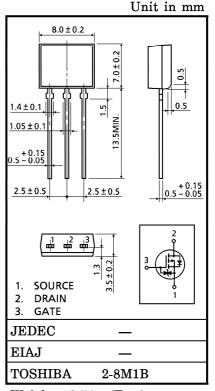
• Enhancement-Mode

:  $V_{th} = -0.8 \sim -2.0 \text{ V}$ ( $V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$ )

### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIS	SYMBOL	RATING	UNIT	
Drain-Source Voltage	$v_{ m DSS}$	-30	V	
Drain-Gate Voltage (RGS	$v_{ m DGR}$	-30	V	
Gate-Source Voltage	$v_{GSS}$	±20	V	
Drain Current	DC	$I_{\mathbf{D}}$	<b>-</b> 5	A
Drain Current	Pulse	$I_{\mathrm{DP}}$	-20	A
Drain Power Dissipation (Ta = 25°C)	PD	1.3	W	
Single Pulse Avalanche	EAS	517	mJ	
Avalanche Current	$I_{AR}$	-5	A	
Repetitive Avalanche En	$\mathrm{E}_{\mathrm{AR}}$	0.13	mJ	
Channel Temperature	$\mathrm{T_{ch}}$	150	°C	
Storage Temperature Ra	$\mathrm{T}_{\mathrm{stg}}$	-55~150	°C	

# INDUSTRIAL APPLICATIONS



Weight: 0.54 g (Typ.)

# THERMAL CHARACTERISTICS

	SYMBOL	·	UNIT	
Thermal Resistance, Channel to Ambient	R <sub>th (ch-a)</sub>	96.1	°C/W	

#### Note:

\* Repetitive rating; Pulse Width Limited by Max. junction temperature.

\*\*  $V_{DD} = -25 \text{ V}$ , Starting  $T_{ch} = 25 ^{\circ}\text{C}$ , L = 14.84 mH $R_{G} = 25 \Omega, I_{D} = -5 A$ 

This transistor is an electrostatic sensitive device. Please handle with caution.

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## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	ern an actenistics	(.a = 25 c)					
CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakag	ge Current	$I_{GSS}$	$V_{GS} = \pm 16  V,  V_{DS} = 0  V$	1	_	±10	$\mu$ A
Drain Cut-off Current		$I_{ m DSS}$	$V_{DS} = -30 \text{ V}, \ V_{GS} = 0 \text{ V}$	_		-100	$\mu$ A
Drain-Source Voltage	e Breakdown		$I_{ m D} = -10  { m mA}, \ { m V}_{ m GS} = 0  { m V}$	-30	_	_	V
Gate Thresh	old Voltage	$ m V_{th}$	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-Source ON Resistance		R <sub>DS</sub> (ON)	$V_{GS} = -4 \text{ V}, I_D = -2.5 \text{ A}$ $V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$	_	0.17	0.2	Ω
Forward Tra Admittance	nsfer	$ Y_{fs} $	$V_{DS} = -10 \text{ V}, I_{D} = -2.5 \text{ A}$	2.0	4.5	_	S
Input Capacitance		$\mathrm{c}_{\mathrm{iss}}$		_	850	_	
Reverse Transfer Capacitance		$C_{rss}$	$egin{aligned} V_{ m DS} = -10   m V, \ V_{ m GS} = 0   m V, \ f = 1   m MHz \end{aligned}$	_	250	_	pF
Output Capacitance		Coss		_	330	_	
Switching Time	Rise Time	t <sub>r</sub>	$V_{GS}$ $V_{OUT}$ $V_{OUT}$	_	50	_	
	Turn-on Time	t <sub>on</sub>	$V_{GS}$ $V_{DD} = -2.5 \text{ A}$ $V_{OUT}$ $R_{L} = 6 \Omega$ $V_{DD} = -15 \text{ V}$	ı	75	_	ns
	Fall Time	tf		_	20	_	lis
	Turn-off Time	toff	$V_{\mathrm{IN}}: \mathrm{t_r},  \mathrm{t_f} < 5  \mathrm{ns}, \ \mathrm{Duty} \leq 1\%,  \mathrm{t_W} = 10  \mu \mathrm{s}$	_	95	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathrm{g}}$	$V_{\mathrm{DD}} = -24 \mathrm{V},  V_{\mathrm{GS}} = -10 \mathrm{V},$	_	27	_	nC
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{\mathrm{D}} = -5 \mathrm{A}$	_	19	_	
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$			8		

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	-5	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	-20	Α
Diode Forward Voltage	${ m v_{DSF}}$	$I_{\mathrm{DR}} = -5 \mathrm{A},  V_{\mathrm{GS}} = 0 \mathrm{V}$		_	1.7	V
Reverse Recovery Time	$t_{rr}$	$I_{DR} = -5 \text{ A}, V_{GS} = 0 \text{ V}$		60	_	ns
Reverse Recovery Charge	$\mathrm{Q}_{\mathrm{rr}}$	$dI_{DR}/dt = 50  A/\mu s$	_	56	_	nC

## **MARKING**

